

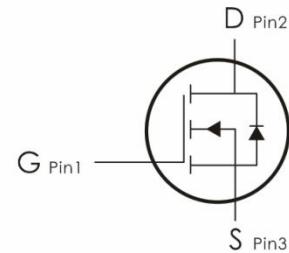
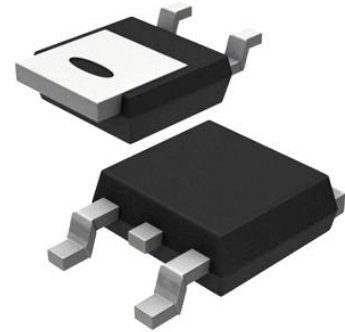
Description:

This P-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge.

It can be used in a wide variety of applications.

Features:

- 1) $V_{DS}=-40V, I_D=-100A, R_{DS(ON)}<5.6m\Omega @V_{GS}=-10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low $R_{DS(ON)}$.
- 5) Excellent package for good heat dissipation.



Package Marking and Ordering Information:

Part NO.	Marking	Package	Packing
CI100P04	CI100P04	TO- 252	2500 pcs/Reel

Absolute Maximum Ratings: ($T_C=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	-40	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current	-100	A
	Continuous Drain Current- $T_C=100^{\circ}C$	-70	
I_{DM}	Pulsed Drain Current ¹	-396	
P_D	Power Dissipation	107	W
E_{AS}	Single pulse avalanche energy ²	576	mJ
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55-+175	$^{\circ}C$

Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.4	$^{\circ}C/W$

Electrical Characteristics: ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Sourctce Breakdown Voltage	V _{GS} =0V, I _D =250 μ A	-40	---	---	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} =0V, V _{DS} =-40V	---	---	-1	μ A
I _{GSS}	Gate-Source Leakage Current	V _{GS} =± 20V, V _{DS} =0A	---	---	± 100	nA
On Characteristics						
V _{GS(th)}	GATE-Source Threshold Voltage	V _{GS} =V _{DS} , I _D =250 μ A	-1	-1.7	2.5	V
R _{DS(ON)}	Drain-Source On Resistance	V _{GS} =-10V, I _D =-20A	---	4.5	5.6	m Ω
		V _{GS} =-4.5V, I _D =-20A	---	6.5	8.3	m Ω
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =-20V, V _{GS} =0V, f=1MHz	---	6637	---	pF
C _{oss}	Output Capacitance		---	544	--	
C _{rss}	Reverse Transfer Capacitance		---	344	---	
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DS} =-20V R _{ENG} =3 Ω , V _{GS} =-10V	---	15	---	ns
t _r	Rise Time		---	16	---	ns
t _{d(off)}	Turn-Off Delay Time		---	67	---	ns
t _f	Fall Time		---	30	---	ns
Q _g	Total Gate Charge	V _{GS} =-10V, V _{DS} =-20V, I _D =-20A	---	117	---	nC
Q _{gs}	Gate-Source Charge		---	12	---	nC
Q _{gd}	Gate-Drain “Miller” Charge		---	21	---	nC
Drain-Source Diode Characteristics						
V _{SD}	Diode Forward Voltage ³	V _{GS} =0V, I _{SD} =-20A	---	---	-1.2	V
I _S	Continuous Drain Curren	VD=VG=0V	---	---	-95	A
I _{SM}	Pulsed Drain Current		---	---	-396	A
T _{rr}	Reverse Recovery Time	I _F =-20A, T _J =25 °C	---	24	---	NS
Q _{rr}	Reverse Recovery Charge	dI/dt=100A/us	---	140	---	NC

Notes:

1.Repetitive Rating: Pulse width limited by maximum junction temperature.

2.EAS condition: $T_J=25^{\circ}\text{C}$, $V_{DD}=15\text{V}$, $V_G=-10\text{V}$, $R_G=25\Omega$, $L=0.5\text{mH}$.

3.Repetitive Rating: Pulse width limited by maximum junction temperature

Typical Characteristics: ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

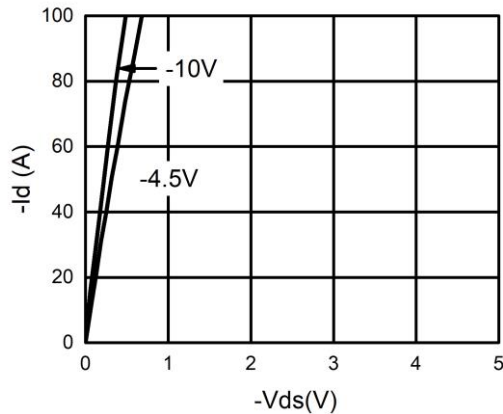


Figure 1. Output Characteristics

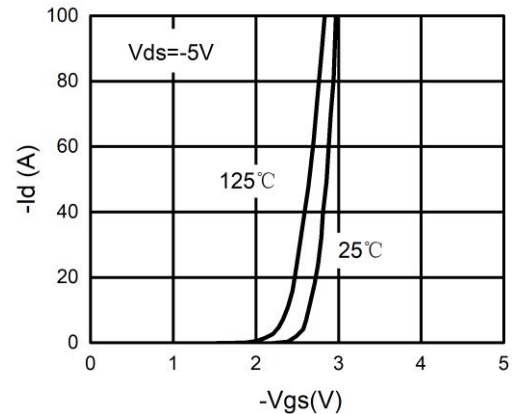


Figure 2. Transfer Characteristics

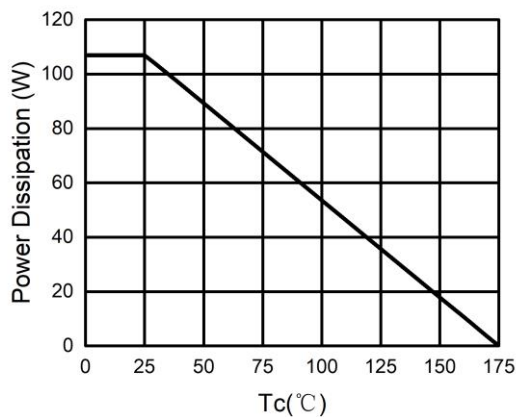


Figure 3. Power Dissipation

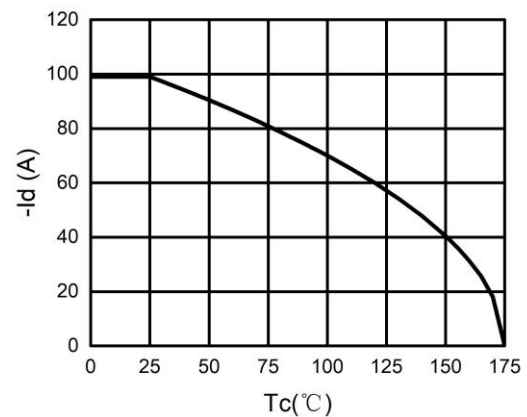


Figure 4. Drain Current

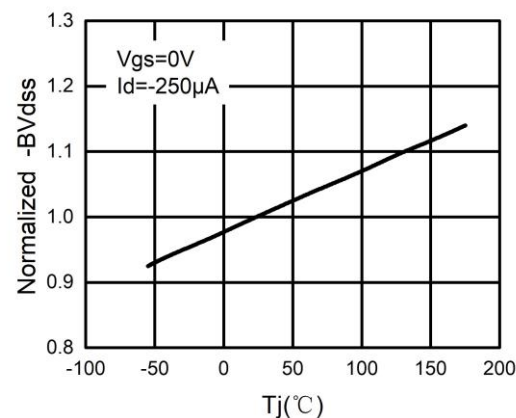


Figure 5. BV_{DSS} vs Junction Temperature

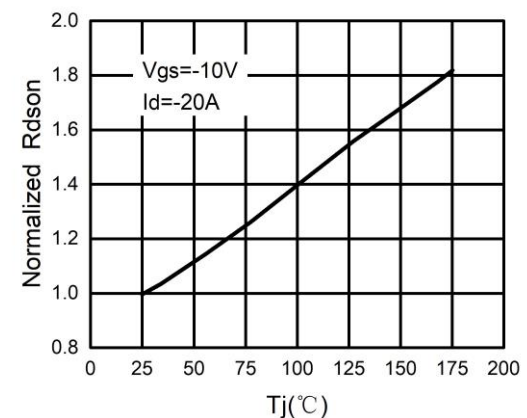


Figure 6. $R_{DS(ON)}$ vs Junction Temperature

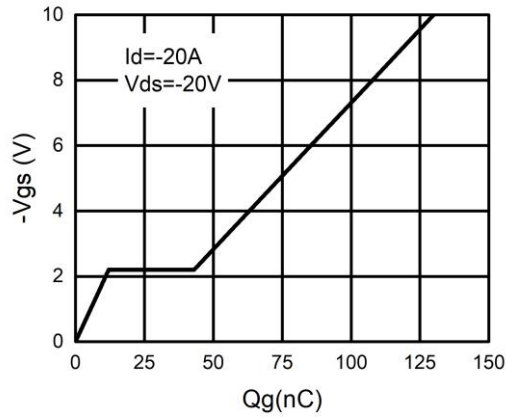


Figure 7. Gate Charge Waveforms

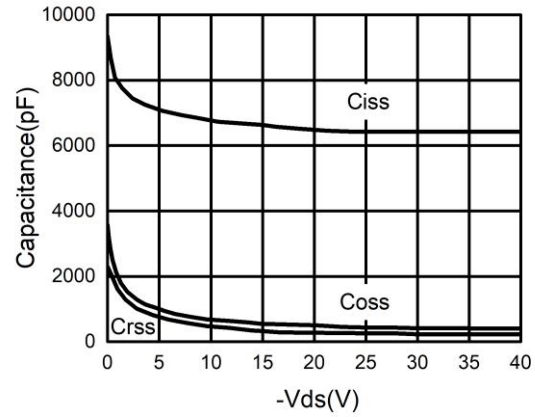


Figure 8. Capacitance

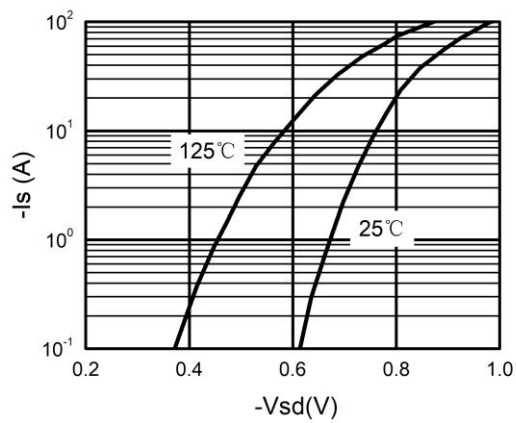


Figure 9. Body-Diode Characteristics

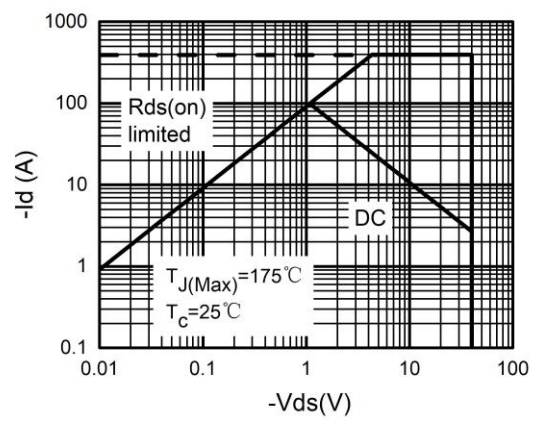


Figure 10. Maximum Safe Operating Area